

AN-1480 LP38859S-1.2 Evaluation Board

1 Introduction

This board is designed to enable the evaluation of the LP38859 voltage regulator. Each board is assembled and tested in the factory. This evaluation board has the TO-263 5–lead package mounted.

2 General Description

The LP38859 is a dual-rail LDO linear regulator capable of supplying up to 3A of output current, and incorporates a Soft-Start feature.

The device has been designed to work with 10 μF input and output ceramic capacitors, and 1 μF bias capacitors. Footprints areas for C_{IN} and C_{OUT} will allow for a variety of sizes.

3 Operation

The input voltage, applied between V_{IN} and GND, should be at least 1.0 V greater than V_{OUT} , and no higher than the applied V_{BIAS} voltage.

The bias voltage, applied between V_{BIAS} and GND should be above the minimum bias voltage of 3.0 V, and no higher than the maximum of 5.5 V.

Loads can be connected to V_{OUT} with reference to GND.

V_{OUT} and V_{IN} test points are provided on the board to allow accurate measurements directly on the evaluation board, eliminating any voltage drop on the PCB traces or connecting wires to the load.

The Soft-Start time for V_{OUT} is an exponential function, and is adjusted by changing the Soft-Start capacitor (C_{SS}) on device pin one. An internal resistor (r_{SS}) and the external capacitor (C_{SS}) form an RC circuit. Five RC time constants is considered to be the Soft-Start time.

$$\text{Soft-Start Time} = 5 \times r_{\text{SS}} \times C_{\text{SS}} \quad (1)$$

The installed soft-start capacitor (C_{SS}) is 10 nF (0.01 μF), and the internal r_{SS} is typically 16 k Ω .

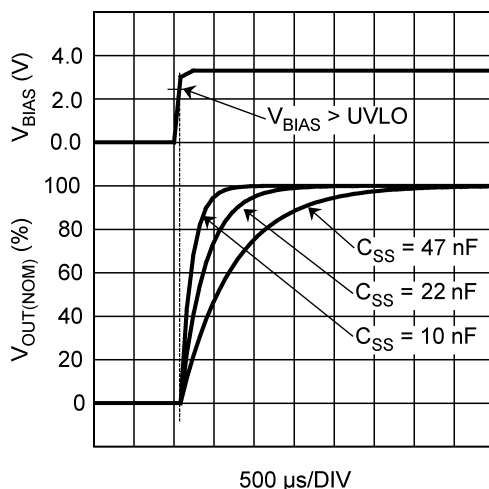


Figure 1. V_{OUT} vs C_{SS}

All trademarks are the property of their respective owners.

4 Hardware

The schematic is shown in Figure 2 and the layout of the evaluation board is shown in Figure 3.

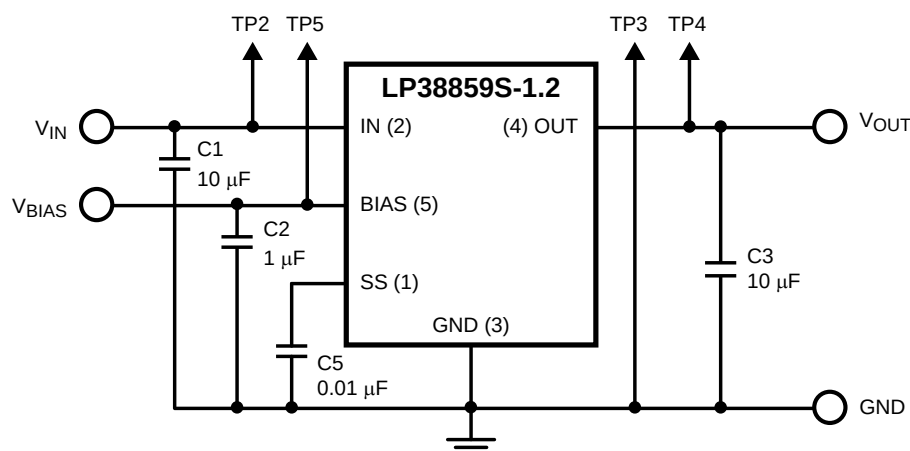


Figure 2. Evaluation Board Schematic

5 PCB Layout

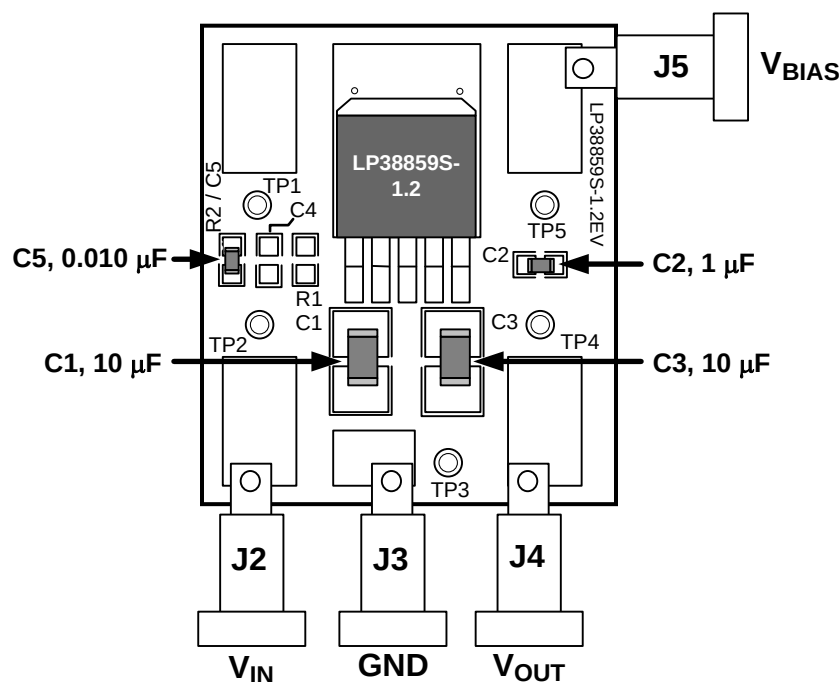


Figure 3. Evaluation Board Component and Pin Layout

6 Power Dissipation

The TO-263 package alone has a junction to ambient thermal resistance (θ_{JA}) rating of 60°C/W. When mounted on the LP38859S evaluation board the θ_{JA} rating is approximately 37°C/W.

Although there is only approximately 0.28 square inches of copper area immediately under the tab, the top copper surface area is extended to additional copper area on the bottom of the board by five thermal vias.

With the 37°C/W thermal rating the LP38859S evaluation board will dissipate a maximum of 2.75W with $T_A = 25^\circ\text{C}$.

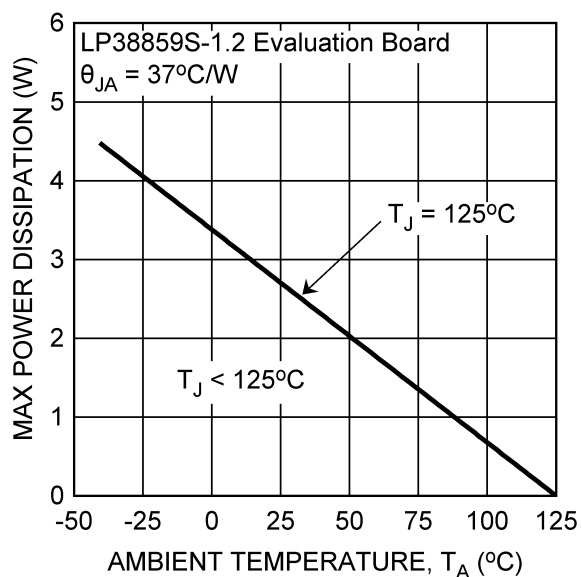


Figure 4. Maximum Power Dissipation vs Ambient Temperature

7 Bill of Materials (BOM)

Table 1. Bill of Materials (BOM)

ID	Name	Description	Manufacturer	Part Number
U1	U1	LP38859	Texas Instruments	LP38859
C1	C _{IN}	10 μ F, 10%, MLCC, 10V, X7R, 1210	AVX	1210ZC106KAT2A
C2	C _{BIAS}	1 μ F, 10%, MLCC, 10V, X7R, 0805	AXV	0805ZC105KAT2A
C3	C _{OUT}	10 μ F, 10%, MLCC, 10V, X7R, 1210	AVX	1210ZC106KAT2A
C4	—	Not Installed	—	—
C5	C _{SS}	0.010 μ F, 10%, MLCC, 16 V, X7R, 0805	AVX	0805YC103KAT2A
J1	—	Not Installed	Johnson Components	—
J2	V _{IN}	Banana Jack : Insulated Solder Terminal - RED		108-0902-001
J3	GND	Banana Jack : Insulated Solder Terminal - BLACK		108-0903-001
J4	V _{OUT}	Banana Jack : Insulated Solder Terminal - ORANGE		108-0906-001
J5	V _{BIAS}	Banana Jack : Insulated Solder Terminal - BLUE		108-0910-001
R1	—	Not Installed	—	—
R2	—	Not Installed	—	—
TP1	—	Not Installed	—	—
TP2	TP _{IN}	Turret Terminal : Mounting Hole Diameter = 0.062"	Keystone	1593-2
TP3	TP _{GND}			
TP4	TP _{OUT}			
TP5	TP _{BIAS}			

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com